

<b>PATENT ASSIGNMENT COVER SHEET</b>
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EPAS ID: PAT6551251

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
QIANQIAN ZHAO	02/08/2021
LIANG XIN	02/08/2021
JINGYI LI	02/08/2021
RUINA BIAN	02/08/2021
DAN YANG	02/08/2021
LIANG QI	02/08/2021
BIN TIAN	02/08/2021
JIAN ZHA	02/08/2021
WENBO YAO	02/08/2021
GENNIAN MAO	02/08/2021
HAN LI	02/08/2021
CHUNYANG SHI	02/08/2021
YONGBO WANG	02/08/2021
JINGWEN XU	02/08/2021

**RECEIVING PARTY DATA**

<b>Name:</b>	SHAANXI UNIVERSITY OF SCIENCE AND TECHNOLOGY
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<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	710021

**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	17175582

**CORRESPONDENCE DATA**

Fax Number:

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**ATTORNEY DOCKET NUMBER:** 10025.0069

**NAME OF SUBMITTER:** FENG SHAN

**SIGNATURE:** /Feng Shan/

**DATE SIGNED:** 02/12/2021

This document serves as an Oath/Declaration (37 CFR 1.63).

**Total Attachments: 3**

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**DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION**

Title of Invention:	PLEUROMUTILIN SALICYLIC ACID ESTER WITH ANTIBACTERIAL ACTIVITY AND A METHOD OF PREPARING THE SAME
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**DECLARATION**

As the below-named inventor(s) (hereinafter designated as the undersigned), I/we hereby declare that:

This declaration is directed to:

- The attached application, or
- United States application or PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_.

The above-identified application was made or authorized to be made by me/us.

I/We believe that I am/we are the original inventor or an original joint inventor of a claimed invention in the application.

I/We hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

**ASSIGNMENT**

Whereas, the undersigned as a sole inventor (if only one name is listed below) or as a joint inventor (if plural names are listed below) has invented certain new and useful improvements in the application identified above.

And, whereas \_\_\_\_\_ SHAANXI UNIVERSITY OF SCIENCE AND TECHNOLOGY

\_\_\_\_\_ (assignee), whose mailing address is \_\_\_\_\_

6 Xuefu Road, Weiyang District, Xi'an, Shaanxi, China 710021

\_\_\_\_\_, is desirous of acquiring the entire right, title, and interest in the same.

Now, for good and valuable consideration, the receipt whereof is hereby acknowledged, I/We, by these presents hereby agree to sell, assign, and transfer unto assignee, and assignee's heirs, successors, and assigns, the full and exclusive right to said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, substitute, and reissue applications, and all Letters Patent, extensions, reissues, and reexamination certificates which may be granted therefore in the United States and its territorial possessions and in any and all foreign countries.

I/We hereby authorize and request the Patent Office Officials in the United States and Its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to assignee as the assignee of my/our entire right, title, and interest in and to the same, for the sole use and behalf of assignee, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me/us had this Assignment and sale not been made.

Further, I/we agree that I/we will communicate to said assignee or its (his) representatives any facts known to me/us respecting said invention, and perform all affirmative acts which may be necessary in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to assignee, make all rightful oaths, and, generally do everything possible to aid assignee, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

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|----|-------------------------|---------------|------|----------------------|
| 1. | Date: <u>2021/02/18</u> | Qianqian      | ZHAO | <u>Qianqian ZHAO</u> |
|    |                         | First         | LAST | Signature            |
|    |                         | Inventor Name |      |                      |
| 2. | Date: <u>2021/02/08</u> | Liang         | XIN  | <u>Liang XIN</u>     |
|    |                         | First         | LAST | Signature            |
|    |                         | Inventor Name |      |                      |
| 3. | Date: <u>2021/2/8</u>   | Jingyi        | LI   | <u>Jingyi LI</u>     |
|    |                         | First         | LAST | Signature            |
|    |                         | Inventor Name |      |                      |
| 4. | Date: <u>2021/02/08</u> | Ruina         | BIAN | <u>Ruina BIAN</u>    |
|    |                         | First         | LAST | Signature            |
|    |                         | Inventor Name |      |                      |
| 5. | Date: <u>2021.02.08</u> | Dan           | YANG | <u>Dan YANG</u>      |
|    |                         | First         | LAST | Signature            |
|    |                         | Inventor Name |      |                      |
| 6. | Date: <u>2021/02/08</u> | Liang         | QI   | <u>Liang Qi</u>      |
|    |                         | First         | LAST | Signature            |
|    |                         | Inventor Name |      |                      |

- |     |                         |               |      |                     |
|-----|-------------------------|---------------|------|---------------------|
| 7.  | Date: <u>2021/2/18</u>  | Bin           | TIAN | <u>Bin TIAN</u>     |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 8.  | Date: <u>2021.02.08</u> | Jian          | ZHA  | <u>Jian ZHA</u>     |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 9.  | Date: <u>2021.02.08</u> | Wenbo         | YAO  | <u>Wenbo YAO</u>    |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 10. | Date: <u>2021.02.08</u> | Gennian       | MAO  | <u>Gennian Mao</u>  |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 11. | Date: <u>2021.2.8</u>   | Han           | LI   | <u>Han LI</u>       |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 12. | Date: <u>2021.02.08</u> | Chunyang      | SHI  | <u>Chunyang SHI</u> |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 13. | Date: <u>2021.02.08</u> | Yongbo        | WANG | <u>Yongbo WANG</u>  |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |
| 14. | Date: <u>2021/02/08</u> | Jingwen       | XU   | <u>Jingwen XU</u>   |
|     |                         | First         | LAST | Signature           |
|     |                         | Inventor Name |      |                     |